AGENDA

8:15 PM  Social – light refreshments will be provided.

8:45 PM  1. Preliminaries and Self-Introductions  Anna Stefanopoulou

Anna called for order and the meeting started with members self-introduction.

8:50 PM  1.1 Student and Young Professional Committee (student travel grant)  Carrie Hall

Carrie introduced the student travel awardees.

8:55 PM  2. Approval of Minutes  Anna Stefanopoulou

Robert asked the motion to approve the last DSCD meeting’s minutes and the minutes was approved.

9:00 PM  3. Update from NSF  Jordan Berg/Irina Dolinskaya

Irina gave an update report from NSF. See the attached report for details.

9:15 PM  4. Conferences and Outreach

4.1 DSCC Steering Committee/2019-2022 DSCC  Santosh Devasia

See the attached report for details.

4.2 AIM 2019-2020  Kok-Meng Lee

KM cannot come join the meeting due to time conflict of 2019 AIM. He sent the report and Robert helped present the attached report.

4.3 ISFA 2020  Robert Landers

Robert presented the attached report on ISFA 2020.

4.4 Newsletter  Jianguo Zhao

Jianguo presented the attached report on Newsletter update.

4.5 DSCD Website  Jeff Shelton

Jeff cannot make the meeting and Robert briefly discussed the website update.
9:40 PM  5. Publications Update

5.1 JDSMC and TMECH                      Joe Beaman/Ranjan Mukherjee/George Chiu
Ranjan presented the attached report on JDSMC update and George cannot make the meeting due to the time conflict of 2019 AIM. Robert helped present the attached report on TMECH.

5.2 DSC Magazine/ASME Letters-DSC        Peter Meckl/Santosh Devasia
Santosh discussed and presented the update on DSC-Letters. The report is attached.

10:00 PM  6. Standing Committee Reports

6.1 Honors and Awards Committee           Santosh Devasia
Santosh discussed and presented the update on Honors Committee. The report is attached.

6.2 Advisory Committee                    Andrew Alleyne
No update is reported by the Advisory Committee.

10:10 PM  7. Open discussion               Anna Stefanopoulou
Anna asked for any open discussions. No outstanding items were discussed.

10:20 PM  8. Closure                       Anna Stefanopoulou
The meeting was adjourned around 10 pm.
• New, unsolicited proposals may be submitted at any time.
• Core Programs only. Solicitations and CAREER still have deadlines.
• Resubmissions: only if substantially revised and at least one year from submission date, regardless of program to which it is submitted.
• No limit to the number of pending proposals as PI or co-PI. However, each proposal must be significantly different and you cannot serve as a panelist if you have a pending proposal in that program.
• Review process and time to receive decision has not change.
• Is there an optimal time to submit a proposal?

Yes ... when you have put together the best possible proposal.
Engineering Directorate (ENG) by the Numbers

Dawn Tilbury, ENG Assistant Director

- **$978 M** FY 2018 research budget
- **13,092** proposals
- **2,458** competitive awards
- **23,697** people supported
- **19%** competitive award success rate
- **9,299** senior researchers
- **1,937** other professionals
- **484** postdoctoral associates
- **7,760** graduate students
- **4,217** undergraduate students

Panels:
- **692** panels
NSF’s 10 BIG IDEAS

RESEARCH IDEAS

- Navigating the New Arctic
- Harnessing Data for 21st Century Science and Engineering
- Work at the Human-Technology Frontier: Shaping the Future
- Understanding the Rules of Life: Predicting Phenotype
- The Quantum Leap: Leading the Next Quantum Revolution
- Windows on the Universe: The Era of Multi-messenger Astrophysics

PROCESS IDEAS

- Growing Convergent Research at NSF
- NSF-Includes: Enhancing Science and Engineering through Diversity
- Mid-scale Research Infrastructure
- NSF 2050: Seeding Innovation
Solicitation NSF 19-511.

One of the NSF’s 10 Big Ideas, NNA tackles convergent scientific challenges in the rapidly changing Arctic that are needed to inform the economy, security, and resilience of the Nation, the circumpolar region and the globe.

Navigating the New Arctic (NNA)

Image from the NSF-funded Polar Geospatial Center

Irina Dolinskaya
NNA Major Goals and Key Components

• Improved understanding of Arctic change and its local and global effects that capitalize on innovative and optimized observation infrastructure, advances in understanding of fundamental processes, and new approaches to modeling interactions among the natural environment, built environment, and social systems.

• New, enhanced research communities that are diverse, integrative, and well-positioned to carry out productive research at the intersections of Arctic natural and built environments and social systems.

• Research outcomes that inform U.S. national security and economic development needs and enable resilient, sustainable Arctic communities.
NSF’s investment in research on the future of work, focusing on difficult and complex research questions surrounding technology innovation, workers, and the interdependencies of technology, human work, lifelong learning, and society.
The Future of Work at the Human-Technology Frontier (FW-HTF)

Analyses of societal, economic, educational and national contexts, including benefits and risks

Fundamental principles and support of individual workers, work teams, workplaces, and work organizations

Engineering & computer science technologies to create human-technology work partnerships
National Science Foundation (NSF)
Dynamic Systems & Control Related Programs

• Core Programs  **ENG: Dawn Tilbury**
  – **Civil Infrastructure Systems (CIS):** Cynthia Chen
  – **Dynamics, Control and Systems Diagnostics (DCSD):** Robert Landers and Irina Dolinskaya
  – **Energy, Power, Control and Networks (EPCN):** Radhakisan (Kishan) Baheti
  – **Mind, Machine and Motor Nexus (M3X):** Robert Scheidt

• Cross-Directorate Programs
  – **Cyber-Physical Systems (CPS):** Robert Landers, Jordan Berg
  – **National Robotics Initiative (NRI):** Irina Dolinskaya, Jordan Berg, Kishan Baheti
  – **Smart and Connected Communities (SCC):** Cynthia Chen, Kishan Baheti, Anthony Kuh

• NSF 10 Big Ideas
  – **Future Work: Human-Technology Frontier (FW-HTF):** Jordan Berg
  – **Navigating the New Arctic (NNA):** Irina Dolinskaya
  – **Harnessing Data Revolution (NDR):** Anthony Kuh
2019 ASME Dynamic Systems and Control Conference
Grand Summit Hotel, Park City, Utah, October 8-11

Updates

• Kam K. Leang (General Chair), University of Utah
• Garrett Clayton (Program Chair), Villanova University
Organizing Committee

General Chair
Kim K. Leang
University of Utah

Program Chair
Garrett Clayton
Villanova University

Local Arrangements Chair
Steve Mascaro
University of Utah

Publicity Chair
Zhang Chen
University of Houston

Publications Chair
Mohammad Al Janadeh
Memorial Univ. of Newfoundland

Workshops & Tutorials Chair
Reza Mohammadi
UT Dallas

Invited/Special Sessions Chair
Carrie Hall
Illinois Institute of Technology - Chicago

Students and Young Members Chair
Matteo Aureli
Univ. of Nevada Reno

Students and Young Members Chair
Nicole Alsaid
Virginia Tech

Conf. Editorial Board Chair
Rifat Stipak
Northeastern University

ASME Program Manager
Edmond Varpoin
Exhibits and Industry Liaison

Manager, Conference Web Tools
Stacey Cooper
Quick updates

Paper reviews completed – accept/reject decision sent to authors

- Total papers submitted for review: 265
- Program Committee met on June 12 to make final accept/reject decisions
- Results
  - Accepted papers: 216
  - Rejected: 49
  - Acceptance rate: 81%
- Final deadlines
  - Copyright due June 28
  - Final paper due July 5 (extended date)
- Registration is open
Late-Breaking-News Poster Session

- Objective is to increase participation and give researchers a chance to share their results.
- Late-Breaking-News poster submission announcement sent on July 3.
  - Authors submit short abstract for review by PC by July 19
  - Acceptance/rejection notice sent by Aug. 1

Basic program at a glance:
Invited Sessions

1. Design, Modeling, Analysis and Control of Assistive and Rehabilitation Devices (Invited session)
2. Energy Optimization for Intelligent Vehicle Systems (Invited session)
3. Advanced Driver Assistance and Autonomous Technologies (Invited session)
5. Modeling and Control of Soft Actuators and Manipulators (Invited session)
6. Vehicle Dynamics and Stability (Invited session)
7. Vibrations: Modeling, Analysis, and Control I (Invited session)
8. Vibrations: Modeling, Analysis, and Control II (Invited session)
9. Renewable and Smart Energy Systems (Invited session)
Special Sessions
1. Industry Perspectives on Controls in Autonomous Systems (organized by the ATS TC) (Special session)
2. Navigating Funding Opportunities at the National Science Foundation (tips for young investigators) (Special session)
3. NSF CAREER Program Panel (Special session)
4. Upcoming Funding Opportunities (info session with program managers, details to TBD) (Special session)

Workshops (Tuesday Oct. 8)
1. Short course on robot control curriculum (Full-day)
2. Practical Methods for Real World Mechatronic Control Systems (Half-day)
3. Stability Analysis of LTI Systems with Time Delays (Half-day)
Student Sessions/Activities
- Student Best Paper judging in progress
- Student networking and advising session (lead by student liaison for the ASME's Energy Systems Technical Committee (ES-TC))

Sponsorships
- University of Utah (Gold, paid $5000)
- Villanova University (Bronze, pending payment $1500)
- Quansar (Bronze, paid $1500)
- SpectraQuest (Bronze, pending payment $1500)
- Deseret UAS (Bronze, paid $1500)

University of Utah campus tour
- Expected Friday, October 11, between 1-4 pm
- Pending support for transportation between hotel and UU
Plenary sessions

Morning Plenary Talk: Wednesday (10/9)
Prof. Allison Okamura
Stanford University
“Soft Robots for Humanity”

Oldenburger Lecture
Thursday (10/10) evening:
Prof. Huei Peng
University of Michigan

Morning Plenary Talk: Thursday (10/10)
Prof. Santosh Devasia
University of Washington
“Synchronized Networks using Delayed Self-Reinforcement”

Nyquist Lecture -- Pending
Tour of venue
Ballroom
Additional facilities
2020 Dynamic Systems and Control Conference

October 4-7, 2020
Pittsburgh, PA, USA
Conference Venue

Venue: Pittsburgh Marriott City Center, Pittsburgh, PA, USA
- Blends style & substance in the heart of Pittsburgh
- Affordable rate: ~$169
Program Committee

General Chair & Program Chair
Jiong Tang (University of Connecticut)
Qingze Zou (Rutgers University)

Committee Members
Xu Chen (University of Washington, Seattle)
Manish Kumar (University of Cincinnati)
Chinedum Okwudire (University of Michigan)
Kenn Oldham (University of Michigan)
Beibei Ren (Texas Tech)
Junmin Wang (University of Texas, Austin)
Yunjun Xu (University of Central Florida)

We Look Forward To Seeing You in Pittsburgh!
Report on
The 2021 ASME DSCC Conference at Austin Texas
Submitted by: Junmin Wang

Conference dates: October 17-20, 2021,
Hotel: Sheraton Austin Hotel At The Capital, Austin, Texas. Located in Downtown Austin, walking distance to the Texas State Capital and many restaurants. DSCC room rate: $205/night.

General Chair:
Junmin Wang
University of Texas at Austin

Program Chair:
Hosam Fathy
Penn State University

Invited and Special Sessions Chair:
Bryan Rasmussen
Texas A&M University

Workshops and Tutorials Chair:
Neera Jain
Purdue University

International Program Co-Chair:
Loucas S. Louca
University of Cyprus

International Program Co-Chair:
Jong-Eun Choi
Yonsei University, South Korea

Local Arrangements Chair:
Dragan Djurdjanovic
University of Texas at Austin

Publicity Chair:
Minghui Zheng
University at Buffalo

Publications Chair:
Beibei Ren
Texas Tech University

Exhibits and Industry Liaison Chair:
Soumik Sarkar
Iowa State University

Students and Young Members Chair:
David Hoelzle
Ohio State University

Conference Editorial Board Chair:
Rifat Sipahi
Northeastern University

Future DSCC Liaison:
TBD
AIM2019: Hosted by Professor Dong Sun (City University of Hong Kong, China) as General Chair, the 2019 IEEE International Conference on Advanced Intelligent Mechatronics (co-sponsored by the ASME Dynamic Systems and Control Division, the IEEE Industrial Electronics Society and the IEEE Robotics and Automation Society) will be held on July 8-12, 2019, Hong Kong Science Park, Hong Kong Munich. Detailed information can be found in the AIM2019 website: https://aim2019.org/.

Submission statistics:
Submissions: 364 Papers, 18 TMECH Papers, and 7 Workshops/Tutorial
Acceptance: 278 papers (76%), 18 TMECH papers and 6 Workshops/Tutorials (37 speakers).

Registration (as of 29 June 2019)

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<th>Qty</th>
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Programs:

A. Workshop/Tutorial
1. Recent Progress on Micromachines and Microrobotics (7 speakers)
2. Automation, Visualization and Interaction in Medical Robotics (8 speakers).
5. Flexible Mechatronics for Robotics and Manufacturing (4 speakers).

B. Plenary/Keynote
1. Research Progress of Intelligent Sensing Technology (Zhuangde Jiang)
2. Digital Printing and Imaging Systems – Old Dog with New Tricks (George T.C. Chiu)
3. Soft Robotics for Industrial Handling (Sadao Kawamura)
4. The Grand Challenges of Science Robotics (Guang-Zhong Yang)
5. Development of Multi-Behavioral Robots (Pei-Chun Lin)
6. Make Motor-Driven Biped Robot Run Robustly and Efficiently (Rong Xiong)
7. High-Accuracy Motion Estimation for MEMS in Complex Environments (Kenn Oldham)
8. Bio-Inspired Cable-Driven Robotic Arms for Safe Manipulation (Guilin Yang)

C. 53 Technical Sessions
1. TMech Paper Presentation (3 sessions)
2. Organized Topics (14 sessions)
3. Regular Papers (36 sessions)

D. Technical Tour to labs at Hong Kong Science Park (Arrow Open Lab, Biomedical Technology Support Centre, Data Studio, IC Failure Analysis Laboratory, Probe and Test Development Centre, Reliability laboratory, Robotics Garage).
AIM2020: Chaired by Professor Jingang Yi (Rutgers University, New Jersey, USA), the 2020 IEEE International Conference on Advanced Intelligent Mechatronics will be held on July 6-9, 2020, Sheraton Boston Hotel, Boston Massachusetts, USA. Detailed information can be found in the AIM2020 website: http://aim2020.org/. Importanat dates for AIM 2020:

- February 14, 2020: Submission of Special & Invited Session Proposals
- February 14, 2020: Submission of Tutorial & Workshop Proposals
- February 28, 2020: Submission of Contributed & Invited Papers
- May 1, 2020: Notification of AIM Paper Acceptance
- May 15, 2020: Final Paper Submission
- June 1, 2020: Advance Registration

AIM is a flagship conference of IEEE/ASME Transactions on Mechatronics (TMech) co-sponsored by the ASME Dynamic Systems and Control Division, the IEEE Industrial Electronics Society and the IEEE Robotics and Automation Society. Through AIM2020, authors of TMech accepted papers (regular and short papers as well as Focused Section papers) will have the following three options to increase broader impacts on mechatronics research:

A. Authors of TMech papers (regular and short papers as well as Focused Section papers) between August 1, 2019 and March 1, 2020 will have the option to present their paper at AIM 2020. This will provide a venue for the TMech authors to promote and highlight their publication to the international mechatronics community. The authors will be able to submit the details of their accepted TMech paper as a presentation only submission (TMech Presentation) in the AIM paper submission site.

B. Concurrent submissions are called for IEEE/ASME TMech and AIM2020, which will be published in a regular TMech issue dedicated to accepted TMech papers with with AIM Presentation. Detailed information and description, including Q&A discussion, about the TMech/AIM2020 concurrent submissions can be found online at http://aim2020.org/contribute/tmech/

- First Submission for TMech: January 8, 2020
- First Decision for TMech: March 6, 2020
- Revised Submission for TMech: March 26, 2020
- Final Decision for TMech and AIM 2020: May 1, 2020
- Final Submission for AIM 2020: May 15, 2020
- Final Submission for TMech: May 15, 2020

For any questions related to the TMech/AIM2020 Call for Paper, please contact:
Xiang Chen, xchen@uwindsor.ca, Senior Editor of TMech/General co-Chair for AIM 2020,
Xiaobo Tan, xbtan@egr.msu.edu, Senior Editor of TMech/Program Chair for AIM 2020.

C. TMech Focused Sections on Selected AIM2020 Papers: Selected papers of AIM 2020 will be invited to submit an extended version to IEEE/ASME TMech for publication consideration in an AIM Focused Section to be published in 2021. The extended version submitted to TMech should contain sufficient and recognizable new contributions and/or results beyond the 2020 AIM paper.

Attached: 1) AIM2020 Call for Papers. 2) TMech/AIM2020 Call for Papers. 3) Presentation slides.
AIM2020: Chaired by Professor Jingang Yi (Rutgers University, New Jersey, USA), the 2020 IEEE International Conference on Advanced Intelligent Mechatronics will be held on July 6-9, 2020, Sheraton Boston Hotel, Boston Massachusetts, USA. Detailed information can be found in the AIM2020 website: http://aim2020.org/. Important dates for AIM 2020:

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B. **Concurrent submissions** are called for IEEE/ASME TMech and AIM2020, which will be published in a regular TMech issue dedicated to accepted TMech papers with with AIM Presentation. Detailed information and description, including Q&A discussion, about the TMech/AIM2020 concurrent submissions can be found online at http://aim2020.org/contribute/tmech/

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<td>First Decision for TMech:</td>
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<td>March 26, 2020</td>
<td>Revised Submission for TMech:</td>
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<td>May 1, 2020</td>
<td>Final Decision for TMech and AIM 2020:</td>
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Attached: 1) AIM2020 Call for Papers. 2) TMech/AIM2020 Call for Papers. 3) Presentation slides.
2020 IEEE/ASME International Conference on Advanced Intelligent Mechatronics (AIM 2020)

Professor Jingang Yi
General Chair, AIM 2020

Presented at 2019 ACC DSCD General Meeting
**Conference Date**

- **July 6–9, 2020** *(other major related conferences: 2020 ACC: July 1-3; 2020 IFAC World Congress: July 12-17)*
- **Technical Program: July 7-9, 2020; Workshops: July 6, 2020**

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</table>
Conference Location – Boston, Mass., USA

- AIM has not been back to US for 15 years! (only twice in US, 1999 in Atlanta, GA, and 2005 in Monterey, CA)

- Boston is the US center for education, research, and innovation (world renown colleges and universities)

- Boston is a culturally interesting, historically rich, and easily access city with mass appeal for diverse audience
Venue: Boston Sheraton Hotel at Copley Place

- 4 miles from Logan International airport, with non-stop service to 46 international destinations ($2.5 by subway)
- Indoor connections to the nearby convention centers
- Abundance of unique off-site venues are in walking distances
- More than 200 upscale shops and restaurants are nearby
- **Room Rates:**
  - $229/night (single/double)
  - Additional person: $40
Organizing Committee

• **General Chair:** Jingang Yi, Rutgers Univ., USA
• **General Co-Chairs:** Xiang Chen, Univ. of Windsor, Canada
  Kiyoshi Ohishi, Nagaoka Univ. of Tech., Japan
  Tao Liu, Zhejiang Univ., China
  Keike Vallery, TU Delft, Netherlands
• **Program Chair:** Xiaobo Tan, Michigan State Univ., USA
• **Program Co-Chairs:** Seiichiro Katsura, Keio Univ., Japan
  Georg Schitter, Vienna Univ. of Tech., Austria
• **Awards Chair:** Gursel Alici, Univ. of Wollongong, Australia
• **Finance Chair:** Kenn Oldham, Univ. of Michigan, Ann Arbor, USA
• **Workshop Chair:** Yang Shi, Univ. of Victoria, Canada
• **Invited Session Chair:** T.-H. Shim, Univ. of Mich., Dearborn, USA
• **Publicity Chair:** Xu Chen, Univ. of Washington, USA
• **Publication Chair:** Garrett Clayton, Villanova Univ., USA
• **Industrial Committee Chair:** Biao Zhang, ABB Inc., USA
• **Registration Chair:** Se Young Yoon, Univ. of New Hampshire, USA
• **Local Arrangement Chair:** Yingzi Lin, Northeastern Univ., USA
New: TMech/AIM Concurrent Submission

• Submission to IEEE/ASME Trans on Mechatronics (TMech) with AIM 2020 presentation only option (i.e., TMech/AIM concurrent submission)
  – Rapidly publish papers in a peer-reviewed, high-impact journal and present at the annual flagship mechatronics conference
  – Promote both the TMech journal and AIM conference

• Why should I take TMech/AIM concurrent submission?
  – One submission to rapidly publish in high-impact journal and disseminate via conference presentation and networking
  – Eligible for TMech Best Papers Award and AIM Best Conference Paper and Best Student Paper Awards (if applied)
# Regular AIM and TMech/AIM Concurrent Submission Timelines

<table>
<thead>
<tr>
<th></th>
<th>TMech Papers (ScholarIOne site)</th>
<th>AIM 2020 Papers (Papercept site)</th>
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<td>February 28, 2020 (Contributed &amp; Invited)</td>
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<td>First-round decision</td>
<td>March 6, 2020</td>
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<td>Revised submission</td>
<td>March 26, 2020</td>
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<td>Final decision</td>
<td>May 1, 2020</td>
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<td>Final submission</td>
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<tr>
<td>Final publication</td>
<td>October 2020 (no. 5)</td>
<td>July 2020</td>
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See you all at AIM 2020 in Boston!
The 2020 IEEE/ASME International Conference on Advanced Intelligent Mechatronics (AIM 2020) will be held on July 6-9, 2020 in Sheraton Boston Hotel at Copley Place, Boston, Massachusetts, USA. As a flagship conference focusing on mechatronics and intelligent systems, the AIM 2020 will bring together an international community of experts to discuss the state-of-the-art, new research results, perspectives of future developments, and innovative applications relevant to mechatronics, robotics, automation, industrial electronics, and related areas.


Call for Papers

Authors are invited to submit IEEE/ASME Transactions on Mechatronics (TMech) Papers with AIM Presentation Option. Paper submissions with this option will be handled in the same manner as contributed papers, and are included in the proceedings. For an extended version submitted to TMech for publication consideration in an AIM Focused Section to be published in 2021, the extended version to IEEE/ASME TMech must contain sufficient and recognizable new contributions and/or results beyond the AIM 2020 paper.

Important Dates

- **January 8, 2020** (for “TMech Papers with AIM 2020 Presentation Option” only): Submission of Basic Paper Information
- **February 14, 2020**: Submission of Tutorial & Workshop Proposals
- **February 28, 2020**: Submission of Contributed & Invited Papers
- **May 1, 2020**: Notification of AIM Paper Acceptance
- **May 15, 2020**: Final Paper Submission
- **June 1, 2020**: Advance Registration

*All deadlines are 23:59pm US PDT.*
Call for Papers

IEEE/ASME Transactions on Mechatronics with AIM 2020 Presentation


Both regular and short papers are solicited. The submitted paper should be no more than 8 T Mech published manuscript pages, excluding photos and bios of authors. The submissions will be subject to a normal peer review process in the standard of T Mech. A Regular Issue of T Mech will be dedicated to publishing all accepted and presented papers in October 2020. As the concurrent submission, the decision for the submitted paper, upon the completed review process in which only one round of major/minor revision is allowed, falls into one of the following two categories:

1. Accepted for publication in T Mech. In this case, the paper will be accepted by AIM 2020 concurrently for presentation and the basic information (abstract, author names and affiliations, etc.) of the accepted paper will be submitted to AIM 2020. The final publication in the dedicated Regular Issue of T Mech, however, will be subject to the presentation of the paper in AIM 2020 with paid registration fee.

2. Rejected for publication in T Mech. In this case, the paper, as well as all review comments, will be forwarded to the Program Committee of AIM 2020 for further consideration. A final acceptance/rejection decision will then be made by the Committee for AIM 2020.

Detailed information and description, including Q&A discussion, about this Call for Paper for T Mech with AIM Presentation can be found online at http://aim2020.org/contribute/tmech/

Manuscript preparation

Papers must contain original contributions and be prepared in accordance with the journal standards. Instructions for authors are available online on the T Mech website.

Manuscript submission

Manuscripts should be submitted to T Mech online at: mc.manuscriptcentral.com/tmech-ieee. The cover letter should include the following statement: “This paper is concurrently submitted for T Mech and AIM 2020 Presentation”. The basic information (abstract, author names and affiliations) of the paper should be submitted concurrently to AIM 2020 online at: ras.papercept.net/conferences/scripts/start.pl.

Submission/Review/Decision Timeline:

- First Submission for T Mech: January 8, 2020
- Basic Paper Information due for AIM 2020: January 8, 2020
- First Decision for T Mech: March 6, 2020
- Revised Submission for T Mech: March 26, 2020
- Final Decision for T Mech and AIM 2020: May 1, 2020
- Final Paper Information due for AIM 2020: May 15, 2020
- Final Submission for T Mech: May 15, 2020

Contacts:

For any questions related to this Call for Paper, please contact:

Xiang Chen, xchen@uwindsor.ca, Senior Editor of T Mech/General co-Chair for AIM 2020,
Xiaobo Tan, xbtan@egr.msu.edu, Senior Editor of T Mech/Program Chair for AIM 2020
2020 International Symposium on Flexible Automation

July 5-9, 2020
Chicago, IL, USA
Conference History: Recent Ten Years

ISFA2012 St. Louis, Missouri
ISFA2014 Awaji-Island, Japan
ISFA2010 Tokyo, Japan
ISFA2016 Cleveland, Ohio
ISFA2018 Kanazawa, Japan
ISFA2018 statistics
• 98 papers accepted (41 long papers; 57 short papers)
• 151 participants (Asia, Europe, North America)
Committee Chairs

Advisory Committee
Masayoshi Tomizuka, University of California at Berkeley, USA
Tohru Watanabe, Ritsumeikan University, Japan

Organizing Committee
Jian Cao, Northwestern University, USA
Hideki Aoyama, Keio University, Japan

Program Committee
Jiong Tang, University of Connecticut, USA
Soichi Ibaraki, Hiroshima University, Japan
Conference Venue

Venue: Embassy Suites by Hilton Chicago Downtown, Chicago, Illinois, USA

- In the heart of downtown Chicago, Illinois, surrounded by shopping and entertainment venues.
- Affordable rate ~$219
- Complimentary cooked-to-order breakfast
Technical Sessions

- Additive manufacturing sensing and control
- Cutting and machine tools
- Digital design and manufacturing
- Flexible automation in manufacturing systems
- Industrial robotics
- Manufacturing controls and machine automation
- Mechatronics and precision manufacturing
- Methodology for manufacturing
- Sensing and information extraction
- Smart and sustainable manufacturing
- Textile and yarn process automation
- Other topics
We Look Forward to Seeing You!

**Main Sponsors**
- The American Society of Mechanical Engineers (ASME)
- The Institute of Systems, Control and Information Engineers (ISCIIE)

*Manuscript submission will begin in November 2019*
DSCD Newsletter: Report at the 2019 ACC Conference

Jianguo Zhao, Tuhin Das, Huazhen Fang
Past Editor: Xu Chen
July 5, 2019
Summary

• The DSCD Newsletter is electronically distributed to the DSCD mailing list every August and December. We publicize call for papers/proposals, conference information, educational activities, introduction of experimental platforms, job postings, as well as special issues in collaboration with guest editors.

• Two issues since last ACC meeting:
  • 2018 summer issue: features division meeting at ACC 2018, member awards, and ISFA 2018 (reported at DSCC 2018)
  • 2018 winter issue: features DSCC 2018, division meeting at DSCC 2018, People in Dynamics & Control, Mechatronics Technical Committee, one article on Time Delay Control, one article on Mechatronics and Robotics Education
2018 Winter Issue

• DSCC 2018
2018 Winter Issue

• The 194th Division Meeting @ DSCC 2018
2018 Winter Issue

• People in dynamics and control

Dr. Huei Peng

Dr. Anna Stefanopoulou
2018 Winter Issue

• The Mechatronics Technical Committee and its Operation

Dr. Jun Ueda

A Look Inside the ASME Dynamic Systems & Control Division (DSCD)

— The Mechatronics Technical Committee and Its Operation

The DSCD currently has six technical committees (TCs) covering, respectively, Automotive and Transportation Systems (ATS), Energy Systems, Biosystems and Healthcare, Mechatronics, Robotics, and Vibrations. In this feature, we speak with Dr. Jun Ueda, Associate Professor and Woodruff Faculty Fellow in the G.W.W. School of Mechanical Engineering at Georgia Institute of Technology and
2018 Winter Issue

• Two Articles

**Analytical and Experimental Predictor-Based Time Delay Control of a High-DOF Robot Manipulator**

M. Bagheri\(^1,2\), P. Naseradinmousavi\(^{++}\), and M. Krstic\(^2\)

\(^{++}\)pnaseradinmousavi@sdsu.edu

\(^1\) Department of Mechanical Engineering, Dynamic Systems and Control Laboratory (DSCL), San Diego State University

\(^2\) Department of Mechanical and Aerospace Engineering, University of California, San Diego

**SIUE School of Engineering’s Lotfi Leads National Advance-ment of Mechatronics and Robotics Education**

Nima Lotfi, PhD

Mechanical Engineering Department

Southern Illinois University Edwardsville
2019 Summer Issue

The 2019 summer issue is planned to be distributed to the community in August 2019.

Please consider making your valuable contributions to future issues.

• Current Staff until December 2019:
  • Editor: Jianguo Zhao, Colorado State University,
    Tel: (970) 491-5927, E-mail: jianguo.zhao@colostate.edu
  • Associate Editor: Tuhin Das, University of Central Florida
    Tel: 407-823-5792, E-mail: Tuhin.Das@ucf.edu
  • Associate Editor: Huazhen Fang, University of Kansas
    Tel: (785) 864-8126, E-mail: fang@ku.edu
To: JSCD Executive Committee  
From: Joseph Beaman, Technical Editor  
Journal of Dynamic Systems, Measurement, and Control (JDSMC)  
Subject: Journal of Dynamic Systems, Measurement and Control Status  
Date: July 2, 2019

Highlights

- Popularity: the journal remains very popular after seeing 554 submissions in 2018 and is on pace for 500+ in 2019.
- Pace: the journal continues to see significant improvements in review times as the total time from submission to Technical Editor decision continues to trend downward.
- Associate Editors: the continued high submission rate of papers necessitates a continuing high number of AEs. We have added 11 new AEs in 2018 and 6 new AEs in 2019.

The Journal of Dynamic Systems, Measurement and Control accepts on-line submissions at: http://journaltool.asme.org/. All papers, from initial submission to final manuscript production files, are handled electronically. Scheduling of specific special journal issues, sending reminders to authors and associate editors, checking production file formatting, and fielding specific journal-related questions and problems continue to be the aspects of journal business that are manually handled.

From 2003 through 2018, there have been 7,406 papers submitted, averaging 494 per year. In 2018, 554 papers were submitted. Since January 1, 2019, there have been 284 papers submitted to the journal. The journal continues with a monthly issue format to meet the high volume of papers. The 2018 issues were published from January through December with a combined total of 187 research papers and 23 technical briefs.

Due to this increased volume, in 2017, the journal has published just over 1,800 pages. In 2018, the journal has published over 2,000 pages. Currently, as of July 2, 2019, the journal has published 1,051 pages with six months left to go in the year. Current issues in production are trending between 175 and 200 pages per issue.

In 2019, the journal has forty-three Associate Editors. Of those, nine (Jongeun Choi, Yonsei Univ.; Yongchun Fang, Cornell Univ.; Mazen Farhood, Virginia Tech; Tesheng Hsiao, National Chiao Tung Univ.; Ryozo Nagamune, Univ. of British Columbia; Srinivasa Salapaka, Univ. of Illinois, Urbana-Champaign; Shankar Coimbatore Subramanian, Indian Institute of Technology – Madras; Zongxuan Sun, Univ. of Minnesota; Ardalan Vahidi, Clemson Univ.) have been on extension assignments in order to finish their
current reviews and will not be taking on any new papers. One AE’s (Junmin Wang, Univ. of Texas at Austin) current term will come up by the end of the year, having completed their second term as AE.

To help reduce the individual Associate Editor workload due to increased submissions and to shorten the amount of time a paper spends in review, we continue to work towards a goal of 40 active Associate Editors. Currently, the workload is on pace to be over 12 reviews per AE. My goal is to keep the AE review load to less than 15 papers a year. To achieve this as we continue to receive a high rate of submissions per year, we would still need a minimum of 40 Associate Editors in the future.

As I conclude my tenure as the Technical Editor, I have focused my energy on being an active and attentive leader, on making the review process more efficient, and supporting the Associate Editors in their work. I have wanted the balance between theoretical and application papers to be maintained and, in the application area, create a blend research applications and societally important applications. We must continue to seek out and encourage both academia and industry to submit to our journal. Our increased visibility and quality of content encourages the continuing high rate of submission.

As we transition to a new technical editor, my ultimate goals are to:

- Support the streamlined review process, maintaining the total amount of time a paper remains under review by:
  - Having papers sent out for review in less than 7 days after being assigned to an Associate Editor
  - Decreasing the time a paper spends in review to under 100 days
  - Holding the average time a paper spends from submission to entering into publication under four months
- Ensure we have a good foundation of responsive Associate Editors that are not overburdened with reviews and have the necessary expertise to support our review needs by:
  - Having a full 40 AEs
  - Averaging less than 15 papers for review per AE
- Maintain the selectivity and importance of the journal by:
  - Holding the rejection rate at over 60%
  - Holding the acceptance rate at below 20%
- Promote the journal to a wide audience by:
  - Promoting the newsletter and expanding its reach
  - Focusing on our visibility and the quality of our publications
- And balance the journal between theory- and application-based articles by:
  - Seeking individuals outside of academia to publish in the journal
  - Seeking Associate Editors from outside of academia
Editor-in-Chief Status Report

George Chiu
gchiu@purdue.edu

Executive Summary:

• 2018 submission: 1517 (down from 1652 in 2017)
• 2019 submission on track to reach 1600
• 3 tier review system instituted in February 2019 with conversation to improve editorial board communication
• Improve TMECH and AIM collaboration
2019 Management Committee

<table>
<thead>
<tr>
<th></th>
<th>2017</th>
<th>2018</th>
<th>2019</th>
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<tbody>
<tr>
<td>Chair</td>
<td>Kok-Meng Lee (DSCD)</td>
<td>Roberto Oboe (IES)</td>
<td>Aaron Dollar (RAS)</td>
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<td>Treasurer</td>
<td>Makoto Iwasaki (IES)</td>
<td>Kyujin Cho (IES)</td>
<td>Xiaobo Tan (DSCD)</td>
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<td>Secretary</td>
<td>Aaron Dollar (RAS)</td>
<td>Kok-Meng Lee (DSCD)</td>
<td>Hiroshi Fujimoto (IES)</td>
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<td>Members</td>
<td>Roberto Oboe (IES)</td>
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<td>Kyujin Cho (RAS)</td>
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<td>Kyujin Cho (RAS)</td>
<td>Aaron Dollar (RAS)</td>
<td>Jun Ueda (DSCD)</td>
</tr>
<tr>
<td></td>
<td>Santosh Devasia (DSCD)</td>
<td>Xiaobo Tan (DSCD)</td>
<td>Roberto Oboe (IES)</td>
</tr>
</tbody>
</table>

Officers of the Management Committee rotate among the sponsoring societies.

2019 Editorial Staff

- **Editor-in-Chief, Elect**: I-Ming Chen, Nanyang Tech. University
- **Editor-in-Chief**: George Chiu, Purdue University (2017-19)
- **Editorial Office**: Ms. Cindy Cory, Purdue University
- **Senior Editors**: 6
- **Technical Editors**: 62
Publication Status

2019 (Vol 24)
• **February issue** – 421 pages, 40 articles
  • Focused Section – Soft Actuators, Sensors, and Components
  • Regular papers – 27 articles
• **April issue** – 479 pages, 44 articles
  • Regular papers – 44 articles
• **June issue** – 536 pages, 50 articles
  • Regular papers – 50 articles
• **July issue** – being finalized, tentatively 45-50 articles

2019 page budget: 3000, pages used (3 issues): 1440
Page Budget and Backlog

Page budget:

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<th>Year</th>
<th>'06</th>
<th>'07</th>
<th>'08</th>
<th>'09</th>
<th>'10</th>
<th>'11</th>
<th>'12</th>
<th>'13</th>
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<th>'16</th>
<th>'17</th>
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<tr>
<td>Pages</td>
<td>750</td>
<td>752</td>
<td>750</td>
<td>794</td>
<td>1028</td>
<td>1224</td>
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<td>3292</td>
<td>3000</td>
<td>3000</td>
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<td>6</td>
<td>6</td>
<td>6</td>
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<td>6</td>
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</table>

• Recommend maintain current 3000 page annual budget and gradually adjust based on submission number

Backlog

• 30 articles in Early Access
• 50 articles published in June 2019 issue
• Target to have a backlog of ~50 early access manuscripts to hand-off to new EiC
Submission Status

- **2019 submission on target to reach 1600**
At-a-Glance Update

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<tr>
<td>Regular paper</td>
<td>477</td>
<td>12</td>
<td>891</td>
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<td>Letter</td>
<td>0</td>
<td>0</td>
<td>1</td>
<td>0.1</td>
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<tr>
<td>Short paper</td>
<td>16</td>
<td>0</td>
<td>31</td>
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<tr>
<td>Focused Section Short Paper</td>
<td>1</td>
<td>0</td>
<td>1</td>
<td>0.1</td>
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<tr>
<td>Focused Section</td>
<td>54</td>
<td>7</td>
<td>73</td>
<td>6.1</td>
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<tr>
<th>Journal Statistics</th>
<th>MTD</th>
<th>Prior 12 Months</th>
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<tr>
<td>Avg. days from submission to first decision</td>
<td>0.0</td>
<td>119.0</td>
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<tr>
<td>Avg. Reviewer turnaround time (days) - Original</td>
<td>0.0</td>
<td>29.1</td>
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<tr>
<td>Avg. Reviewer turnaround time (days) - Resubmission</td>
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<tr>
<td>Avg. Reviewer turnaround time (days) - Revision</td>
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<td>Avg. Time to Assign Reviewer (days) - Original</td>
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<td>11.9</td>
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<tr>
<td>Avg. Time to Assign Reviewer (days) - Resubmission</td>
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<tr>
<td>Avg. Time to Assign Reviewer (days) - Revision</td>
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<td>11.0</td>
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<tr>
<td>Avg. days from submission to final decision</td>
<td>0.0</td>
<td>117.3</td>
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<table>
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<tr>
<th>Other Statistics</th>
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<tbody>
<tr>
<td>Accept Ratio (prior 12 months)</td>
<td>144 : 503 ( 28.6%)</td>
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</table>
# Impact Factor and Ranking

## New data just out for 2018

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<tbody>
<tr>
<td>Rank in Engineering, Manufacturing</td>
<td>1</td>
<td>1</td>
<td>1</td>
<td>4</td>
<td>6</td>
<td>49</td>
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<tr>
<td>Rank in Automation and Control Systems</td>
<td>3</td>
<td>3</td>
<td>6</td>
<td>10</td>
<td>11</td>
<td>62</td>
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<tr>
<td>Rank in Engineering, Mechanical</td>
<td>3</td>
<td>5</td>
<td>3</td>
<td>9</td>
<td>7</td>
<td>129</td>
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<tr>
<td>Rank in Engineering, Electrical &amp; Electronics</td>
<td>17</td>
<td>12</td>
<td>25</td>
<td>38</td>
<td>36</td>
<td>265</td>
</tr>
</tbody>
</table>

- Two new journals in additive manufacturing moved to the top of the Manufacturing Engineering category
Three Tier Editorial Structure

• Implementation delayed till February 2019
  • S1M process backlog
• 6 Senior Editors (SE) started:
  • Michael Basin, Autonomous University of Nuevo Leon, Mexico (IES)
  • Xiang Chen, University of Windsor, Canada (ASME)
  • Marcia O’Malley, Rice University, US (RAS, ASME)
  • Hong Qiao, Chinese Academy of Science, China (RAS)
  • Xiaobo Tan, Michigan State University, US (ASME)
  • Wenjun Zhang, University of Saskatchewan, Canada (IES)
• Added Conversation Tool in S1M to facility editorial board communication
• Additional 6 Senior Editor have been selected an will start in January 2020.
Call for Technical Editors

• Qualification
  • Associate Professor with tenure or equivalent industry experience and above
  • Active participation in TMECH and AIM
  • Able to cover at least three TMECH technical areas listed in: https://engineering.purdue.edu/TMECH/

• Nomination:
  • CV + Statement of interest with summary of publications in TMECH and participations in AIM
  • Email to George Chiu (gchiu@purdue.edu) or I-Ming Chen (michen@ntu.edu.sg)

• Especially in need of expertise in fluid powers, vehicle powertrains, design science, and power electronics
TMECH+AIM

• TMECH submissions that are accepted before AIM paper submission deadline are given the option to present at the following AIM.
• Pilot implementation since Fall 2018, remind authors of accepted TMECH paper the opportunity to present their work at the 2019 AIM
• Among 120+ accepted TMECH papers, 18 papers have submitted to 2019 AIM – 3 sessions in a single track on the first day of the conference
AIM Focused Section in 2020 TMECH

• AIM CEB Chair will invite authors of selected 2019 AIM papers to submit an extended version for possible publication in 2020 TMECH AIM Focused Section

• CEB Chair will serve as the Focused Section Senior Editor and form guest editorial board to handle the review of the submitted papers

• Tentative schedule
  • October 2019 – initial submission
  • January 2020 – First decision
  • March 2020 – Revision received
  • June 2020 – Acceptance decision
  • August 2020 – Final file submission
  • October 2020 – Publication
VISION

The *Dynamic Systems and Control Magazine* aims to be the professional forum for the members of the ASME Dynamic Systems and Control Division, with an emphasis on the highest quality expository articles on important and emerging topics, society events, and people active in the division.
Background

- Dynamic Systems and Control Magazine has been published quarterly (March, June, September and December) since beginning of 2013 as a 24-page supplement to ASME Mechanical Engineering Magazine.

<table>
<thead>
<tr>
<th></th>
<th>Cost</th>
<th>Circulation</th>
<th>Editor</th>
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</thead>
<tbody>
<tr>
<td>2013-2014</td>
<td>$12,000 per issue</td>
<td>All ASME members</td>
<td>Galip Ulsoy</td>
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<tr>
<td>2015-2016</td>
<td>$28,200 per issue</td>
<td>All ASME members</td>
<td>Peter Meckl</td>
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<tr>
<td>2017-2019</td>
<td>$15,000 per issue</td>
<td>DSCD primary and secondary members</td>
<td>Peter Meckl</td>
</tr>
</tbody>
</table>
Recent Issues – 2015-16
Recent Issues – 2017-18
Final Issue
Reasons for Ending DSC Magazine

• Inclusion of DSC Magazine in major indexes (e.g., Engineering Index, Google Scholar, Web of Science) has not occurred consistently. This is partly because it was published as part of ME magazine.

• Each issue cost $15,000, for a total of $60,000 per year. This represents a significant share of the total annual DSCD budget and is unsustainable.
Next Steps

• DSCD ExCom is considering a new publication, Dynamic Systems and Control Letters.
• Santosh Devasia has prepared a proposal to ASME to start this new publication in 2021.
• The new publication would be handled like JDSMC, so it would be indexed and it would not cost the Division anything other than a commitment to provide papers and an Editorial Board.
ASME Letters: Dynamics Systems and Controls (L-DSC)

Santosh Devasia
Mechanical Engineering
University of Washington
Why L-DSC?

1. **Goal:** A well-indexed, high-visibility publication to disseminate high-interest information from the dynamic systems and controls community.

2. **Rationale:**
   1. Successful in publishing the magazine with similar articles.
   2. Strong editorial boards (magazine and conference) in place. They have shown the ability to deliver high quality work.
   3. Not cost us, e.g., as the DSC Magazine to publish.
What is L-DSC (ideally)?

1. Indexed in ISI, Scopus, etc.
2. Publishes short review-type articles of broad interest (including industry and students),
3. Articles on educational efforts.
4. Brief Announcements: Publishes articles on upcoming and past events such as conferences (similar to Controls systems magazine)
5. Publish short letters (six pages) from our conference DSCC
The how (process, details)

1. DSCD ExCom meetings
2. Survey DSCD Community (March 2019)
3. Discussed with J DSMC Editors (current + past)
4. Discussed with ASME about process & draft proposal
5. Discussion at DSCD ExCom meetings
6. Second Survey of authors with accepted papers in DSCC (June/July): strong interest
7. Discussion at Division meeting at ACC
8. If positive, move for approval from ASME and implement
1. Some issues from ExCom

1. Not compete with Journal of DSMC (discussed with current and new Editor). 600+ submissions to JDSMC so no issues there.

2. Can have announcements, editorials? Yes 10%

3. What is the minimal number of articles needed for ISI or web of science indexing? 60 per year, 4 issues

4. Overlap with other Letters? Tight coupling with DSCC

5. When can we start? 2021. Accepted papers will be online by end of Nov/Dec 2019

6. Transition from magazine to letters: Members from magazine editorial board. Peter Meckl will be the initial Editor.
2. Highlights from DCSD Survey (March 2019)

• A great initiative that could benefit both members (perhaps, junior faculty in particular) and the Division as a whole. This could increase DSCC submission as well.

• Even though I just started as the new Editor-in-Chief of the Systems & Control Letters, I am not concerned about overlap. It is probably minimal, if any. SCL is traditionally mathematically leaning.

• It would be a good move, keeping in line with peer societies.

• It would be great to do a focused issue on education (both tools and techniques).
2. Highlights from DCSD Survey (March 2019)

- It may be a good idea to ultimately replace DSC Magazine by DSC-L, unless there are major concerns to do so.
- Great idea. My only suggestion is to consider more frequent issues -- quarterly publication is somewhat at odds with the idea of rapid publication. I would suggest monthly. (Papers will appear as soon as accepted even though issues will be later on)
- The Letters format is a great way to get the benefit of conference presentations with a more rigorous peer review process. Options for Open-Source publications with DSC-L will also be great.
- One concern was potential challenges with ASME J-DSMC
3. Discussion: journal editors

1. Does not compete with Journal of DSMC (discussed with current and new Editor).
   600+ submissions to JDSMC so no issues there.

2. Issue with sufficient number of AEs for both Journal and Letters:
   **Approach:** Leverage conference review process.
   1. Some members from the Conference Editorial Board (can be junior members of our community) serve on a Letters Editorial Board (ASME is OK with this).
   2. CEB chair is also an AE in the Letters

3. Improve impact of Journal. New editor is reviewing approaches to speed up review processes further.
4. Survey of authors with 2019 DSCC papers

1. Very positive to publication in L-DSC
2. Authors indicated interest for 48 potential papers from 2019 DSCC to be potentially published in L-DSC

We should retain this interest from the community as it could also help improve quality of DSCC
Web of Science (WoS)

Upon publication of the first issue, ASME will submit the journal for review for inclusion in the Web of Science (WoS):
http://wokinfo.com/products_tools/multidisciplinary/esci/

Evaluation starts after 3 consecutive issues are received. The journal may be accepted immediately into the Web of Science, Emerging Sources Citation Index (ESCI) or the Web of Science, Science Citation Index Expanded (SCIE): http://wokinfo.com/essays/journal-selection-process/

The earliest that a WoS journal impact factor (JIF) will be available is after the third year of publication:
http://wokinfo.com/essays/impact-factor/
6. Process for joint submission

<table>
<thead>
<tr>
<th>April start</th>
<th>Submit to DSCC. Indicate interest in L-DSC</th>
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<tbody>
<tr>
<td>May end</td>
<td>CEB (chair AE of Letters) recommends accepted papers to L-DSC</td>
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<tr>
<td>June</td>
<td>Editor invites (some) Authors to submit to L-DSC</td>
</tr>
<tr>
<td>July</td>
<td>Author submits final paper to DSCC and L-DSC, pays registration fees to conference</td>
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<tr>
<td>Sept</td>
<td>1st Review of DSCC-L</td>
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<tr>
<td>October</td>
<td>Author presents paper at DSCC</td>
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<tr>
<td></td>
<td>Paper appears in the preliminary DSCC proceeding</td>
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<tr>
<td>Oct end</td>
<td>L-DSC completes second review (if needed)</td>
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<tr>
<td>Nov</td>
<td>Letters-accepted papers are then pulled out of the final conference proceedings.</td>
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<td></td>
<td>If not accepted to Letters, papers will remain in Final Conference Proceedings</td>
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<tr>
<td>Dec</td>
<td>Accepted papers to L-DSC appear online</td>
</tr>
</tbody>
</table>
Summary

1. **Goal**: A well-indexed, high-visibility publication to disseminate high-interest information from the dynamic systems and controls community

2. Potential joint submission with DSCC

3. Enables news items without additional cost to division.

4. Strong community interest from DSCC 2019 authors

5. ASME willing to act quickly and launch in 2019 so we can include papers from DSCC 2019

6. Please note additional comments in the notepad

7. Questions?
ASME DSCD Honors & Awards Committee (HAC)

**Chair:** Santosh Devasia (2019)
**Vice-Chair:** Kim Stelson (2021)

**Members:**
Oldenburger Medalist

- 5 strong nominations.
- Huei Peng recommended by DSCD Awards Committee
- Selected by ASME and accepted by Huei Peng.
2019 Awards

• Nominations for the two “odd year” awards were due at the end of June:
• Yasundo Takahashi Education Award (6 nominations)
• Outstanding Young Investigator Award (8 nominations)
• Best paper award will also be selected in Summer
• Selections will be made over the summer, and the awardees will be notified in July/August. The awards will be given at the DSCC banquet.
New members needed

• 3 potential turnovers in the HAC in 2019
• Please send an email to Anna in case you are interested in serving on the committee